

## Abstract of Presentation

### Microstructure control and critical current density of MgB<sub>2</sub> tapes and wires

#### Abstract :

A Powder-In-Tube(PIT) method is the most popular method to fabricate MgB<sub>2</sub> tapes and wires. However, PIT processed tapes and wires show relatively low J<sub>c</sub> values due to the low density and, hence, low connectivity of MgB<sub>2</sub> cores. Some hydrocarbon addition to the starting powder is effective to increase the connectivity of MgB<sub>2</sub> grains and J<sub>c</sub> values. We found that the addition of C<sub>9</sub>H<sub>12</sub> to the powder mixture(MgH<sub>2</sub>+B) significantly increased J<sub>c</sub> from 3,3kA/cm<sup>2</sup> to 13kA/cm<sup>2</sup> at 4.2K and 10T. Co-addition of C<sub>9</sub>H<sub>12</sub> and SiC is more effective to enhance J<sub>c</sub> values. Malic acid (C<sub>4</sub>H<sub>6</sub>O<sub>5</sub>) addition is also reported to be effective to enhance the connectivity of MgB<sub>2</sub> grains and J<sub>c</sub> values. However, these J<sub>c</sub> values are still far below the practical level.

Recently, we succeeded in the fabrication of MgB<sub>2</sub> tapes having high density MgB<sub>2</sub> core applying a hot pressing. Starting tapes were prepared by an in situ PIT process. The mixture of boron powder and MgH<sub>2</sub> powder was put into Fe tube, and cold rolled into tape with 5mm in width and 0.5mm in thickness. We tried out co-doping of nano-sized SiC powder and C<sub>9</sub>H<sub>12</sub> to the powder mixture in order to improve superconducting properties. The tapes were hot-pressed under 100MPa at 630oC in argon gas atmosphere for 1 to 10 hours. For comparison conventional 1 atm. heat treatment using a tube furnace was also carried out. The reduction of MgB<sub>2</sub> cross sectional area was obtained by the hot pressing, ~0.44mm<sup>2</sup> for the hot pressed tape and ~0.55mm<sup>2</sup> for the conventionally heat treated tape. This indicates the increase of the MgB<sub>2</sub> core density from ~50% for the conventional heat treatment to ~70% for the hot pressing. MgB<sub>2</sub> grain connectivity estimated by the Rowell's method was also improved from 17.4 to 21.7 by the hot pressing. Hot pressed pure MgB<sub>2</sub> tape showed I<sub>c</sub> of 38A at 4.2K and 10T which was about three times as large as the I<sub>c</sub> of conventionally heat treated tape. I<sub>c</sub> of the hot pressed and conventionally heat treated tapes with co-doping were 200A and 140A at 4.2K and 10T, respectively. These I<sub>c</sub> values correspond to the J<sub>c</sub>(for MgB<sub>2</sub> layer) values of 45kA/cm<sup>2</sup> and 25kA/cm<sup>2</sup> in 10T, respectively. The magnetic field dependence of J<sub>c</sub> of the hot-pressed tape is almost equal to that of the conventionally heat treated tapes, suggesting that the improvement in J<sub>c</sub> is due to enhanced grain connectivity associated with the increase in the MgB<sub>2</sub> density rather than to the introduction of pinning centers. These results clearly indicate that the hot pressing is effective in increasing the density of MgB<sub>2</sub> core and hence, in enhancing J<sub>c</sub> values of PIT processed MgB<sub>2</sub> tapes. Further enhancement of connectivity and J<sub>c</sub> values may be obtained by the optimization of hot

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pressing conditions.

Another effective method to increase MgB<sub>2</sub> core density is an internal Mg diffusion (IMD) process. We applied this process to the fabrication of MgB<sub>2</sub> round wires. A pure Mg rod was placed at the center of a Ta tube, and the space between the Mg rod and the Ta tube was filled with B powder or with B-SiC mixed powder. The composite can be cold worked into wire with ~1mm diameter at room temperature. We also fabricated 7- and 19-filamentary wires applying similar method. Finally the wires were heat treated at 600 ~ 700 °C for 0.25-10hr. During the heat treatment, Mg diffused into the B layer and reacted with B to form MgB<sub>2</sub>. The reacted layer is not MgB<sub>2</sub> single phase but contained some amount of impurity phases such as MgB<sub>4</sub>. Reacted MgB<sub>2</sub> layer thickness is sensitive to the heat treatment conditions. The thickness of MgB<sub>2</sub> layer rapidly increases with increasing the heat treatment temperature. However, higher J<sub>c</sub> can be obtained for lower heat treatment temperature probably due to the small grain size. Furthermore, reproducibility of J<sub>c</sub> values becomes worse when the heat treatment temperature is higher than 650°C (melting point of Mg). Vickers hardness of MgB<sub>2</sub> layer in the IMD processed wires is around 1300 which is much higher than that of PIT processed wire. This suggests that the density of MgB<sub>2</sub> layer is much higher than that of PIT processed wire. The highest J<sub>c</sub> values (calculated for the reacted layer) are 100kA/cm<sup>2</sup> in 10T at 4.2K for 7-filamentary wires and 4.9kA/cm<sup>2</sup> in 5T at 20K for 19-filamentary wire. These J<sub>c</sub> values are much higher than those of usual PIT processed wires. The increase of the number of filaments, i.e. the decrease of the MgB<sub>2</sub> layer thickness will further increase the J<sub>c</sub> values. Now the filaments in the wire have irregular shape because we firstly apply groove rolling with square cross section and then we apply drawing with dies for the wire fabrication. The decrease of this irregularity of filament shape will be effective in increasing the J<sub>c</sub> values. The void formation at the center of each filament is one of the problems that should be solved in the future.